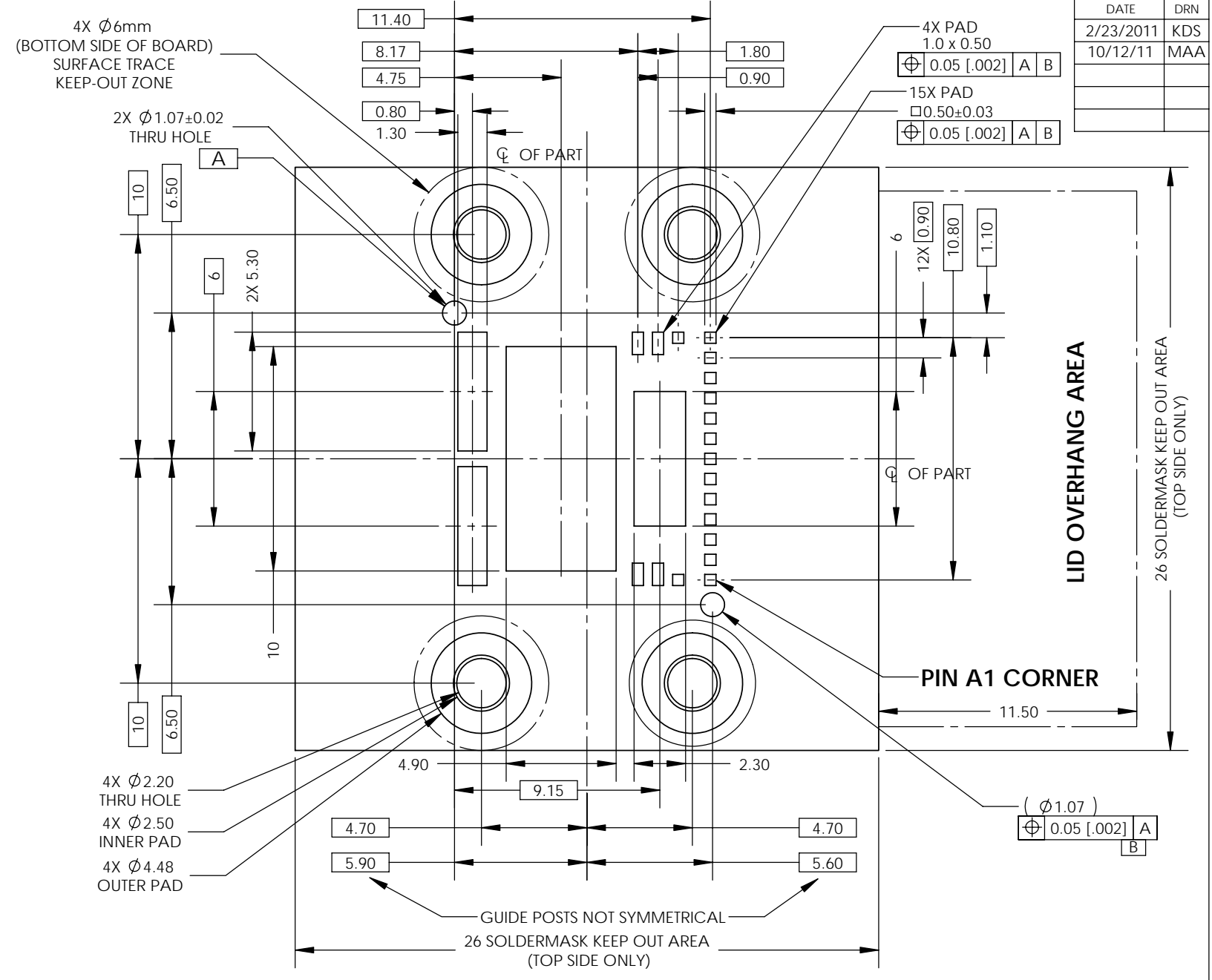
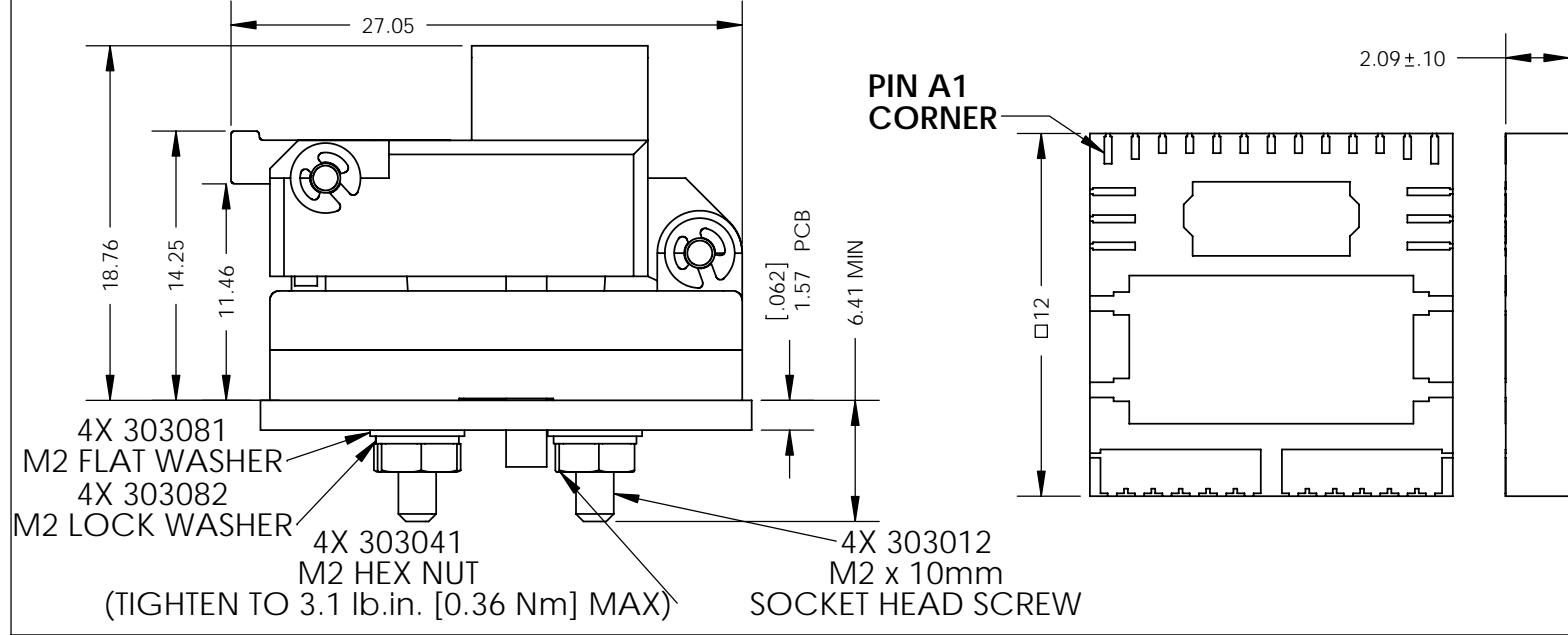
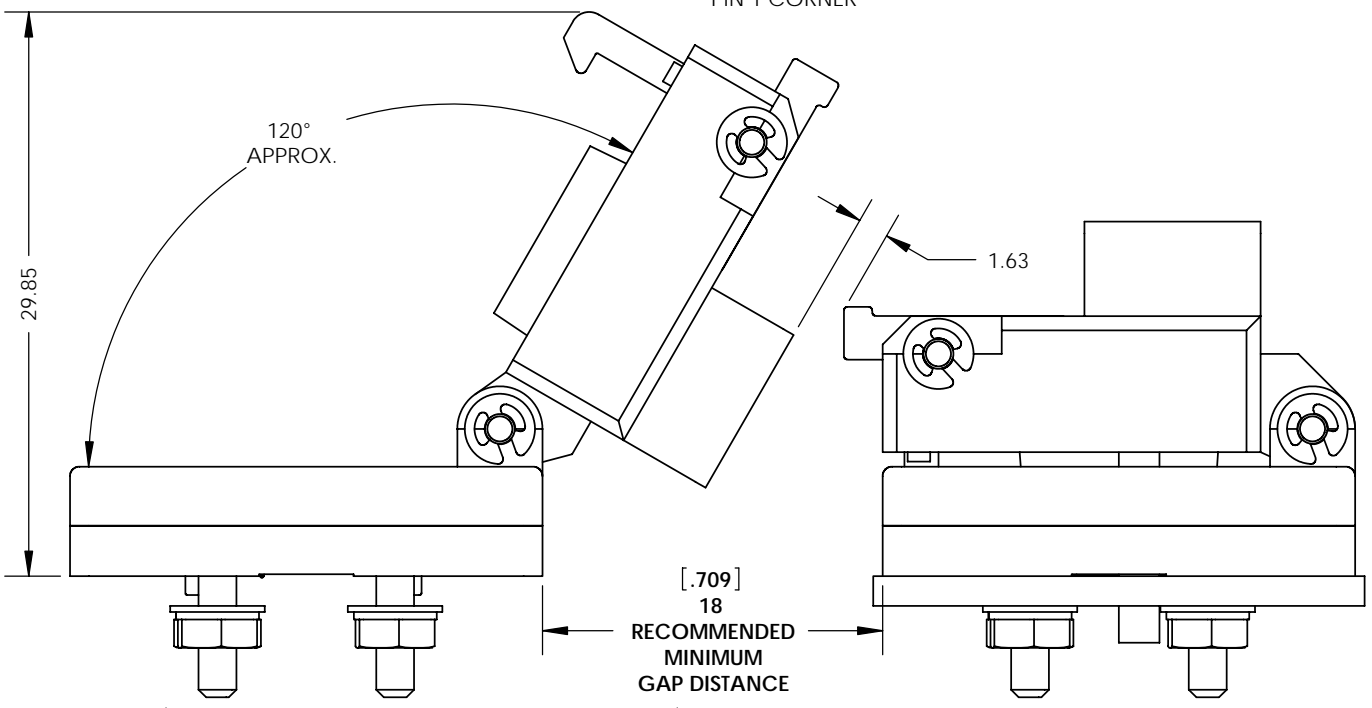
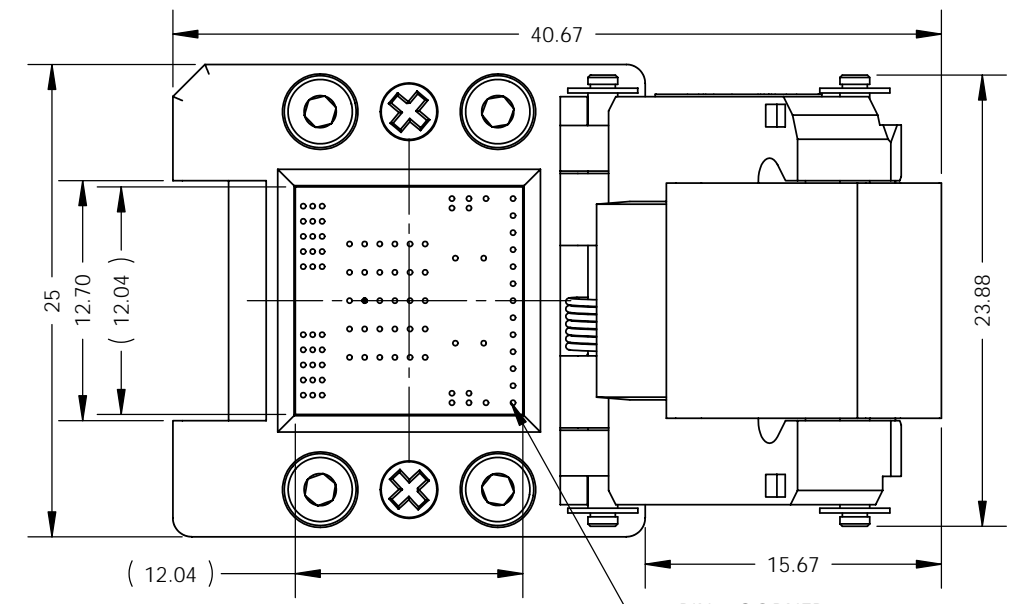


DATE	DRN
2/23/2011	KDS
10/12/11	MAA



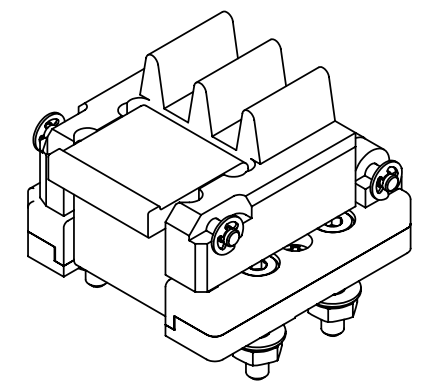
TOP VIEW OF BOARD

NOTES:

1. PCB PAD PLATING: 30 µin. HARD Au OVER 300 µin. Ni OVER 1oz. MIN. Cu
2. ALL Au PADS SHOULD BE SAME THICKNESS.
3. BOARD LAYOUT TOLERANCE: ± .05.
4. NO FILLED VIAS.
5. VIAS MUST BE OFFSET FROM CONTACT PADS.

P/N: 87QHCHS02

PROPRIETARY



- FEATURES:**
- PIN = H038LL1A
 - ALUM. HEAT SINK LID

THIS DRAWING IS SUBJECT TO CHANGE WITHOUT NOTICE. PLEASE REQUEST A CURRENT DRAWING WHEN LAYING OUT BOARDS.	SIZE: B	NAME: KDS	DATE: 2/23/11	DWG NO. S87QHCHS02	SHEET 1 OF 1
	DRAWN	CHECKED		TITLE: C-SERIES LGA H-PIN, 12.0 x 12.0mm DEVICE, MIXED PITCH, 87x H-PINS	
SCALE: VAR.	ENG APPR.				
UNITS: mmgs	MFG APPR.				
SOLIDWORKS CREATED FILE					